film without causing significant bubble formation during the vacuum drying step while ensuring a highly uniform film thickness after drying. Thus, the invention aims to provide a photosensitive resin composition by using a combination of organic solvents with specific characteristics to reduce bubble formation during the vacuum drying step so that an excellent photosensitive resin film with a uniform thickness is obtained after drying.

[SUMMARY]

[0006a]

In a first aspect, there is provided a photosensitive resin composition comprising at least one resin (a) selected from the group of polyimide, polybenzoxazole, a precursor of polyimide, and a precursor of polybenzoxazole; a photosensitive agent (b); an organic solvent (c) with a boiling point of 100°C or more and 130°C or less under atmospheric pressure; and an organic solvent (d) with a boiling point of 150°C or more under atmospheric pressure and a viscosity of more than 1.1 mPa·s and less than 1.5 mPa·s at 20°C, wherein the component (c) accounts for 40 wt% or more and 90 wt% or less of the total quantity of the organic solvents while the component (d) accounts for 10 wt% or more and 60 wt% or less of the total quantity of the organic solvents.

[0006b]

In a second aspect, there is provided a photosensitive resin film production method comprising the step (1) of discharging a photosensitive resin composition as defined herein from a slit nozzle onto a substrate to form a coating film and the step (2) of vacuum-drying the coating film.

[0006c]

In a third aspect, there is provided a photosensitive resin film with a film thickness of 5 μm or more and 10 μm or less produced by the production method as defined herein.

[Means of solving the problems]

[0007]

The invention provides a photosensitive resin composition comprising at least one resin (a) selected from the group of polyimide, polybenzoxazole, a precursor of polyimide, and a precursor of polybenzoxazole, a photosensitive agent (b), an organic solvent (c) with a boiling point of 100°C or more and 130°C or less under atmospheric pressure, and an organic solvent (d) with a boiling point of 150°C or more under atmospheric pressure and a viscosity of more than 1.1 mPa·s and less than 1.5 mPa·s at 20°C, wherein the component (c) accounts for 40 wt% or more and 90 wt% or less relative to the total quantity of the organic solvents while the component (d) accounts for 10 wt% or more and 60 wt% or less relative to the total quantity of the organic solvents.

[Effect of the invention]

[0008]